Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. **(Currently amended)** A multilayer ceramic electronic part having

an external electrode(s) formed from a thermosetting conductive paste which is then cured, said thermosetting conductive paste comprising conductive particles of Ag having a high melting point of 400°C or more, Sn metal powder having a melting point of 300°C or less and a thermosetting resin(s), the thermosetting resin(s) being bisphenol-type epoxy resin and resol-type phenol resin in combination, and wherein the Sn metal powder ~~having a melting point of 300°C or less~~ is present in an amount by weight based on the total weight of said Ag conductive particles ~~having a high melting point~~ and said Sn metal powder

~~having a melting point of 300°C or less~~, of from 5% to 17.6% and an internal electrode(s) comprising Ni.

2. **(Currently amended)** The multilayer ceramic electronic part according to claim 1, wherein the total content of said Ag conductive particles ~~having a high melting point~~ and said Sn metal powder having a melting point of 300°C or less in said thermosetting conductive paste is in the range of 70 to 95% by weight relative to the total weight of said Ag conductive particles ~~having a high melting point~~, said Sn metal powder ~~having a melting point of 300°C or less~~, and said resin(s).

3. **(Cancelled)**

4. **(Currently amended)** A multilayer ceramic electronic part obtained according to a method comprising the steps of:

(1) providing a thermosetting conductive paste comprising Ag conductive particles having a high melting point of 400°C or more, Sn metal powder having a melting point of 300°C or less and

a thermosetting resin(s), the thermosetting resin(s) being bisphenol-type epoxy resin and resol-type phenol resin in combination, and a ceramic composite body, having an internal electrode(s) comprising Ni, which composite body is to be provided with an external electrode(s);

(2) printing or applying said thermosetting conductive paste on or to a surface(s) where an internal electrode(s) of said ceramic composite body is led out; and

(3) maintaining said ceramic composite body obtained in the step (2) at a temperature of 80°C to 400°C for a period of one to sixty minutes so as to cure said thermosetting conductive paste and form the external electrode(s); and wherein the Sn metal powder ~~having a melting point of 300°C or less~~ is present in an amount by weight based on the total weight of said Ag conductive particles ~~having a high melting point~~ and said Sn metal powder ~~having a melting point of 300°C or less~~, of from 5% to 17.6%.

5. **(Previously presented)** The multilayer ceramic electronic part according to claim 4, wherein said conductive particle in said external electrode(s) makes a diffused junction with the Ni of said internal electrode(s) of said multilayer ceramic composite body.

6. **(Previously presented)** The multilayer ceramic electronic part according to claim 4, wherein said multilayer ceramic electronic part is selected from the group consisting of a capacitor, a capacitor array, a thermistor, a varistor, an LC composite part, a CR composite part, an LR composite part, and an LCR composite part.

7. **(Cancelled)**

8. **(New)** The multilayer ceramic electronic part according to Claim 1 wherein the surface of the external electrode(s) is plated to enhance adhesive strength for solder mounting.

9. **(New)** The multilayer ceramic electronic part according to Claim 8 wherein the surface of the external electrode(s) is plated with nickel.

10. **(New)** The multilayer ceramic electronic part according to Claim 4 wherein the surface of the external electrode(s) is plated to enhance adhesive strength for solder mounting.

11. **(New)** The multilayer ceramic electronic part according to Claim 10 wherein the surface of the external electrode(s) is plated with nickel.